Chipsmall

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

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We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!
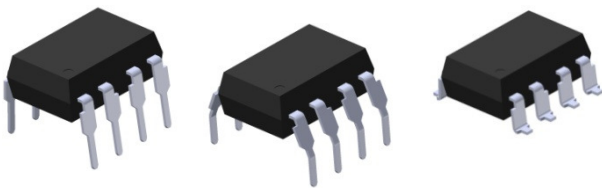

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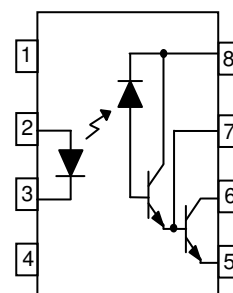
EVERLIGHT

DATASHEET

8 PIN DIP LOW INPUT CURRENT HIGH GAIN SPLIT DARLINGTON PHOTOCOUPLER
6N138 6N139

Schematic

Pin Configuration
1. No Connection
2. Anode
3. Cathode
4. No Connection
5. Gnd
6. Vout
7. V_B
8. Vcc

Features

- High current transfer ratio–2000% typical
- High isolation voltage between input and output (Viso=5000 Vrms)
- Guaranteed performance from 0℃ to 70℃
- Pb free and RoHS compliant.
- UL approved (No. 214129)
- VDE approved (No. 132249)
- SEMKO approved
- NEMKO approved
- DEMKO approved
- FIMKO approved
- CSA approved (No. 2037145)

Description

The 6N138 and 6N139 devices each consists of an infrared emitting diode, optically coupled to a high gain split Darlington photo detector. They provide extremely high current transfer ratio between input and output, with access to a base terminal to adjust the gain bandwidth.These devices are packaged in an 8-pin DIP package and available in wide-lead spacing and SMD options.

Applications

- Digital logic ground isolation
- RS-232C line receiver
- Low input current line receiver
- Microprocessor bus isolation
- Current loop receiver

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Absolute Maximum Ratings (Ta=25℃)

	Parameter		Symbol	Rating	Unit
Input	Forward current		I_F	20	mA
	Peak forward current (50% duty, 1ms P.W)		I_{FP}	40	mA
	Peak transient current (≤1μs P.W,300pps)		I_{Ftrans}	1	A
	Reverse voltage		V_R	5	V
	Power dissipation		P_{IN}	45	mW
Output	Power dissipation		P_O	100	mW
	Output current		IO	60	mA
	Emitter-Base Reverse Voltage		VER	0.5	V
	Output voltage	6N138 / 6N139	V_O	-0.5 to 7 / -0.5 to 18	V
	Supply voltage	6N138 / 6N139	V_{CC}	-0.5 to 7 / -0.5 to 18	V
Isolation voltage [1]			V_{ISO}	5000	V rms
Operating temperature			T_{OPR}	-40 ~ +85	℃
Storage Temperature			T_{STG}	-55 ~ +125	℃
Soldering temperature [2]			T_{SOL}	260	℃

Notes:
  *1 AC for 1 minute, R.H.= 40 ~ 60% R.H. In this test, pins 1, 2, 3, 4 are shorted together, and pins 5, 6, 7, 8 are shorted together.

  *2 For 10 seconds

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Electrical Characteristics (T_A=0 to 70℃ unless specified otherwise)

Input

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Forward voltage	V_F	-	1.3	1.7	V	I_F = 1.6mA
Reverse Voltage	V_R	5.0	-	-	V	I_R = 10µA, T_A=25℃
Temperature coefficient of forward voltage	$\Delta V_F/\Delta T_A$	-	-1.8	-	mV/℃	I_F =1.6mA

Output

Parameter		Symbol	Min	Typ.	Max.	Unit	Condition
Logic High Output Current	6N138	I_{OH}	-	0.01	100	µA	I_F=0mA, V_O=V_{CC}=18V
	6N139		-	-	250		
Logic Low Supply Current	6N138	I_{CCL}	-	0.6	1.5	mA	I_F=1.6mA, V_O=Open, V_{CC}=18V
	6N139						
Logic High Supply Current	6N138	I_{CCH}	-	0.05	10	µA	I_F=0mA, V_O=Open, V_{CC}=18V
	6N139						

Transfer Characteristics (T_a=0 to 70℃ unless specified otherwise, Vcc=4.5V)

Parameter		Symbol	Min	Typ.	Max.	Unit	Condition
Current Transfer Ratio	6N139	CTR	400	2500	-	%	I_F = 0.5mA, V_O = 0.4V, V_{CC}=4.5V
			500	2000	-		I_F = 1.6mA, V_O = 0.4V, V_{CC}=4.5V
	6N138		300	2000	-		
Logic Low Output Voltage	6N139	V_{OL}	-	0.05	0.4	V	I_F = 0.5mA, I_O = 2mA, V_{CC}=4.5V
			-	0.09	0.4		I_F = 1.6mA, I_O = 8mA, V_{CC}=4.5V
			-	0.12	0.4		I_F = 5mA, I_O = 15mA, V_{CC}=4.5V
			-	0.17	0.4		I_F = 12mA, I_O = 24mA, V_{CC}=4.5V
	6N138		-	0.06	0.4		I_F = 1.6mA, I_O = 4.8mA, V_{CC}=4.5V

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Switching Characteristics   (T$_a$=0 to 70℃ unless specified otherwise, Vcc=5V)

Parameter		Symbol	Min	Typ.	Max.	Unit	Condition
Propagation Delay Time to Logic Low (Fig. 13)	6N139	TPHL	-	5	25	μs	I$_F$ = 0.5mA , R$_L$=4.7kΩ, T$_A$=25℃
			-	-	30		I$_F$ = 0.5mA , R$_L$=4.7kΩ
			-	0.2	1		I$_F$ = 12mA , R$_L$=270Ω, T$_A$=25℃
			-	-	2		I$_F$ = 12mA , R$_L$=270Ω
	6N138		-	1.4	10		I$_F$ = 1.6mA , R$_L$=2.2kΩ, T$_A$=25℃
			-	-	15		I$_F$ = 1.6mA , R$_L$=2.2kΩ
Propagation Delay Time to Logic High (Fig. 13)	6N139	TPLH	-	16	60	μs	I$_F$ = 0.5mA , R$_L$=4.7kΩ, T$_A$=25℃
			-	-	90		I$_F$ = 0.5mA , R$_L$=4.7kΩ
			-	1.7	7		I$_F$ = 12mA , R$_L$=270Ω, T$_A$=25℃
			-	-	10		I$_F$ = 12mA , R$_L$=270Ω
	6N138		-	8	35		I$_F$ = 1.6mA , R$_L$=2.2kΩ, T$_A$=25℃
			-	-	50		I$_F$ = 1.6mA , R$_L$=2.2kΩ
Common Mode Transient Immunity at Logic High (Fig. 14) [*3]		CM$_H$	1,000	-	-	V/μs	I$_F$ = 0mA , V$_{CM}$=10Vp-p, R$_L$=2.2KΩ, T$_A$=25℃
Common Mode Transient Immunity at Logic Low (Fig. 14) [*3]		CM$_L$	1,000	-	-	V/μs	I$_F$ = 1.6mA , V$_{CM}$=10Vp-p, R$_L$=2.2KΩ, T$_A$=25℃

* Typical values at T$_a$ = 25℃

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Typical Electro-Optical Characteristics Curves

Fig.1 LED Forward Current vs. Forward Voltage
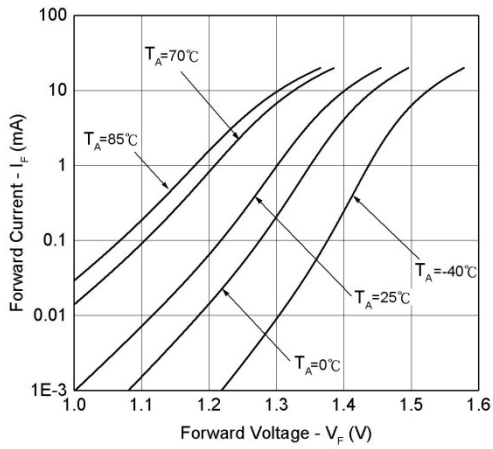
Fig.2 LED Forward Voltage vs. Temperature
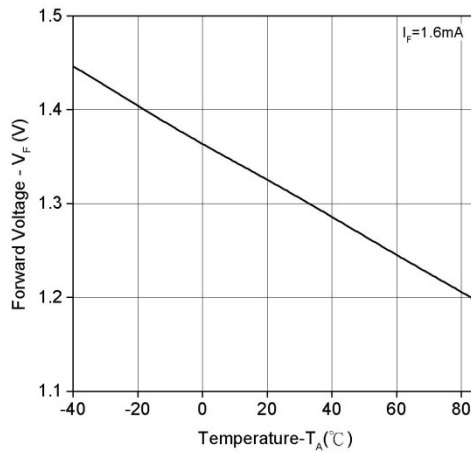
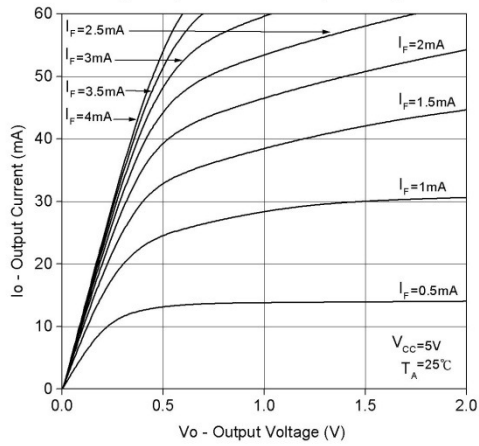Fig.3 Output Current vs. Output Voltage
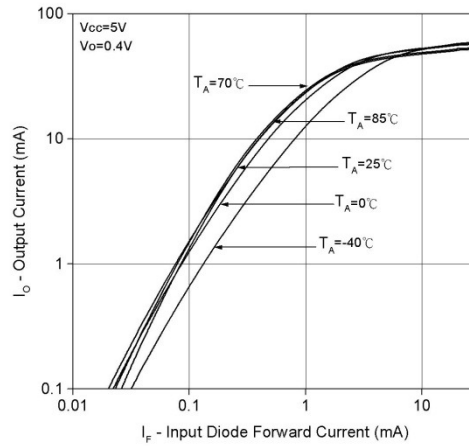
Fig.4 Output Current vs. Input Diode Forward Current
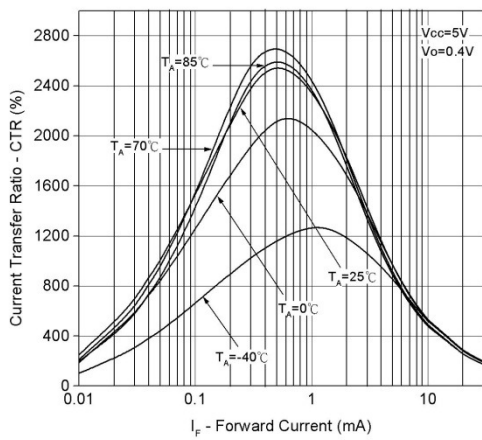
Fig.5 Current Transfer Ratio vs. Forward Current

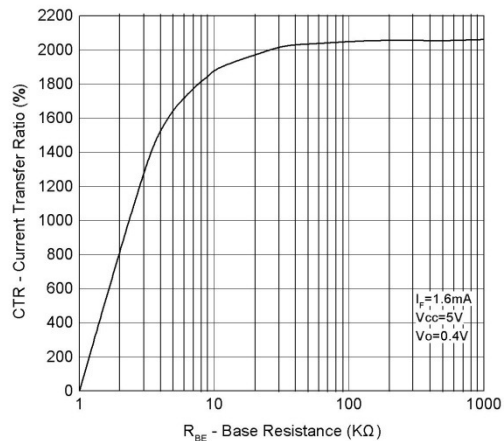Fig.6 Current Transfer Ratio vs. Base-Emitter Resistance

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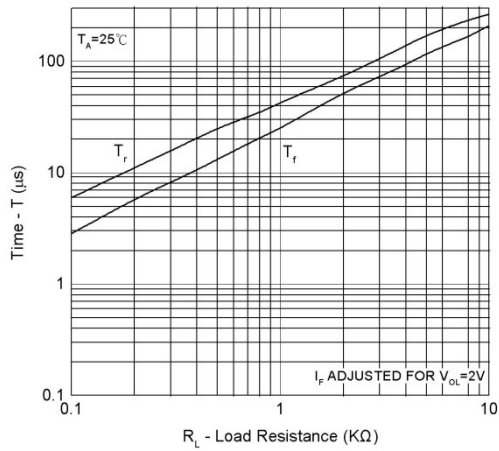
Fig.7 Non-saturated Rise nand Fall Times vs. Load Resistance
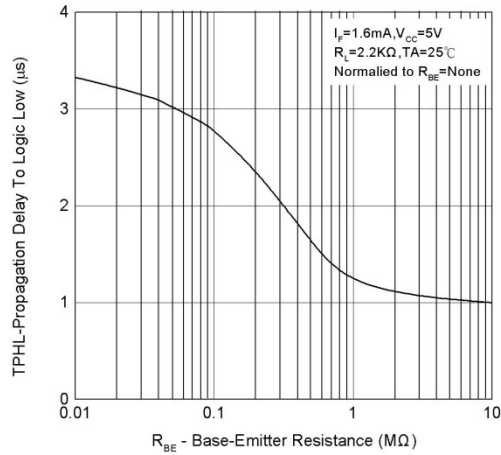

Fig.8 Propagation Delay To Logic Low vs. Base-Emitter Resistance

Fig.9 Propagation Delay vs. Input Diode Forward Current
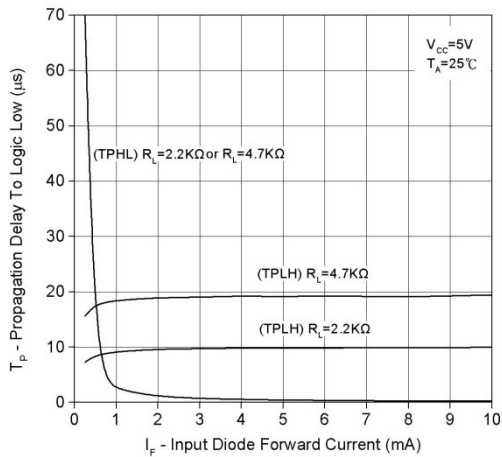
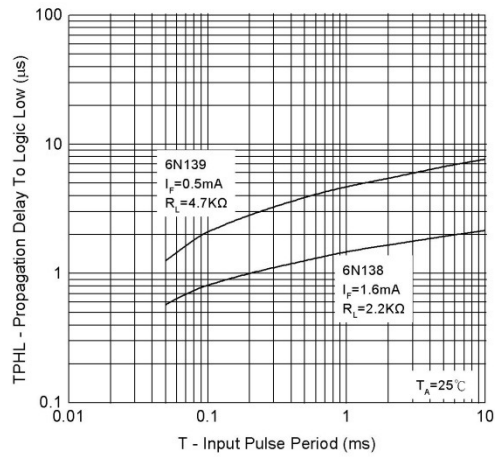Fig.10 Propagation Delay to Logic Low vs. Pulse Period

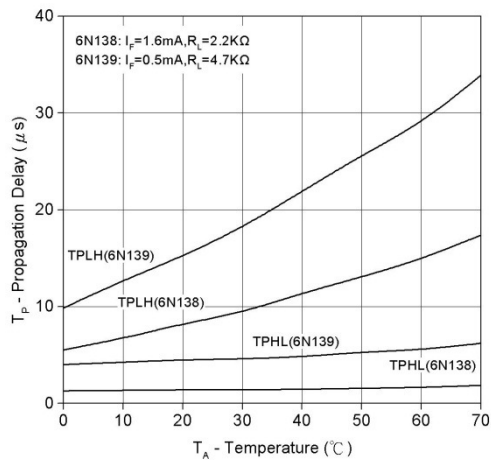Fig.11 Propagation Delay vs. Temperature

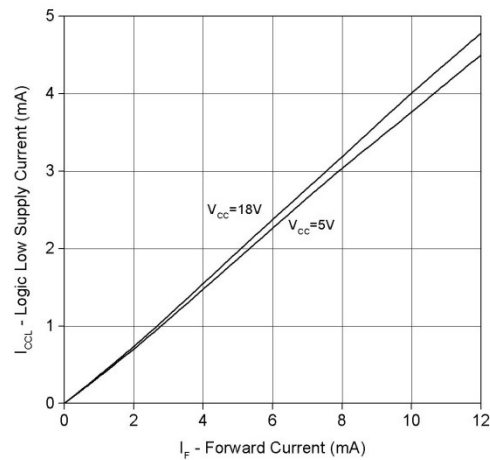Fig.12 Logic Low Supply Current vs. Input Diode Forward Current

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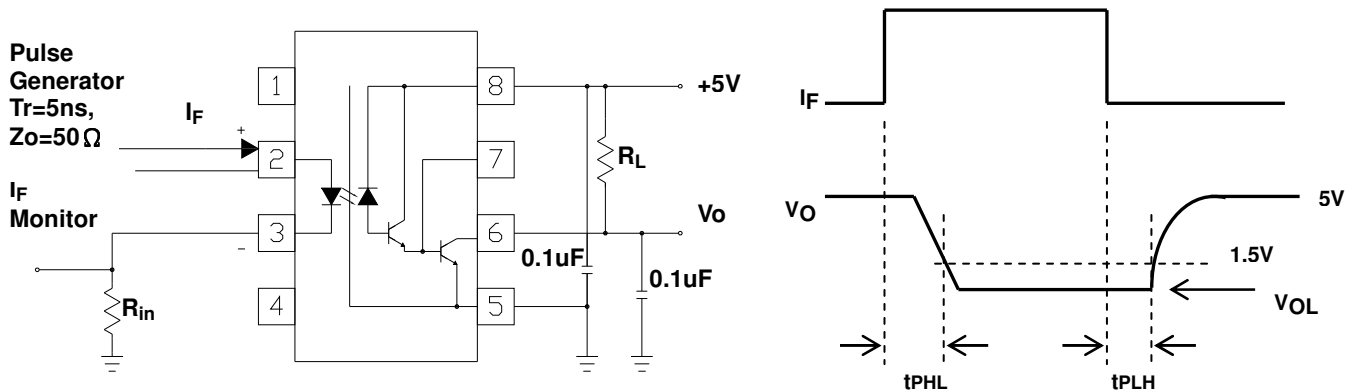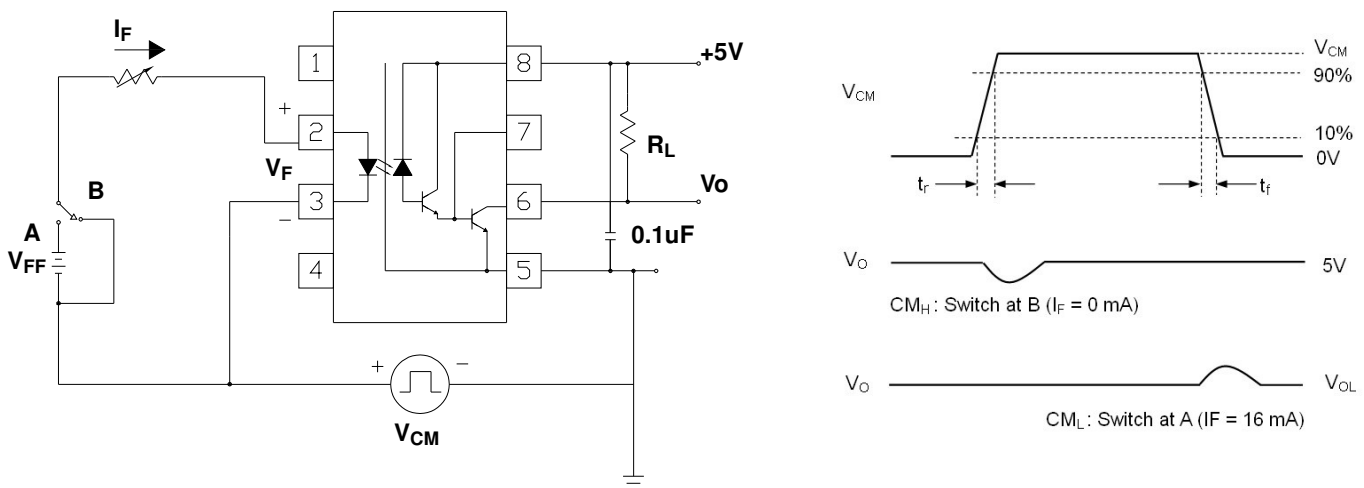## Fig. 13 Switching Time Test Circuit and Waveform

Fig. 14 Common Mode Transient Immunity Test Circuit and Waveform

Note:

*3 Common mode transient immunity in logic high level is the maximum tolerable (positive) dVcm/dt on the leading edge of the common mode pulse signal VCM, to assure that the output will remain in a logic high state (i.e., VO > 2.0V).

Common mode transient immunity in logic low level is the maximum tolerable (negative) dVcm/dt on the trailing edge of the common mode pulse signal, VCM, to assure that the output will remain in a logic low state (i.e., VO < 0.8V).

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Order Information
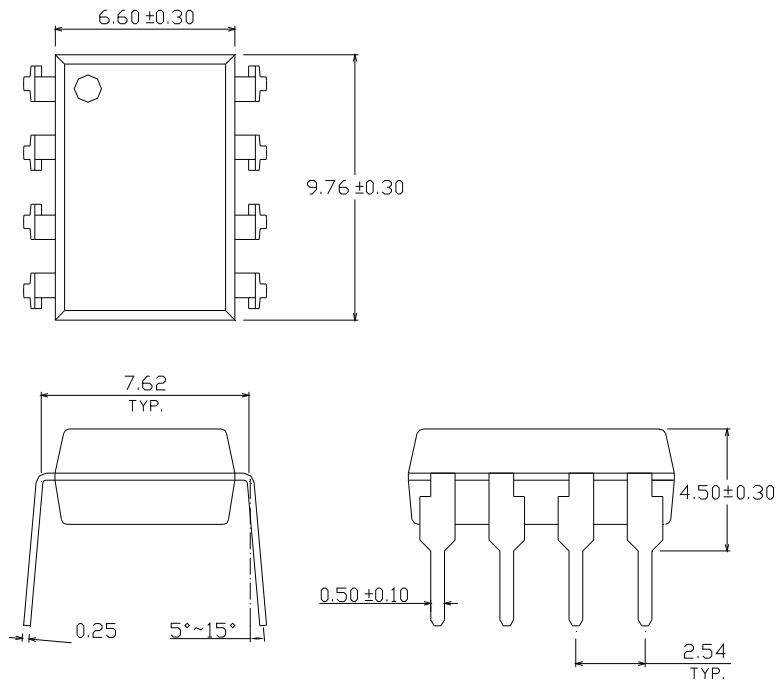
Part Number

6N13XY(Z)-V

Note

X   = Part No. (X = 8 or 9)
Y   = Lead form option (S, S1, M or none)
Z   = Tape and reel option (TA, TB or none).
V   = VDE (optional)
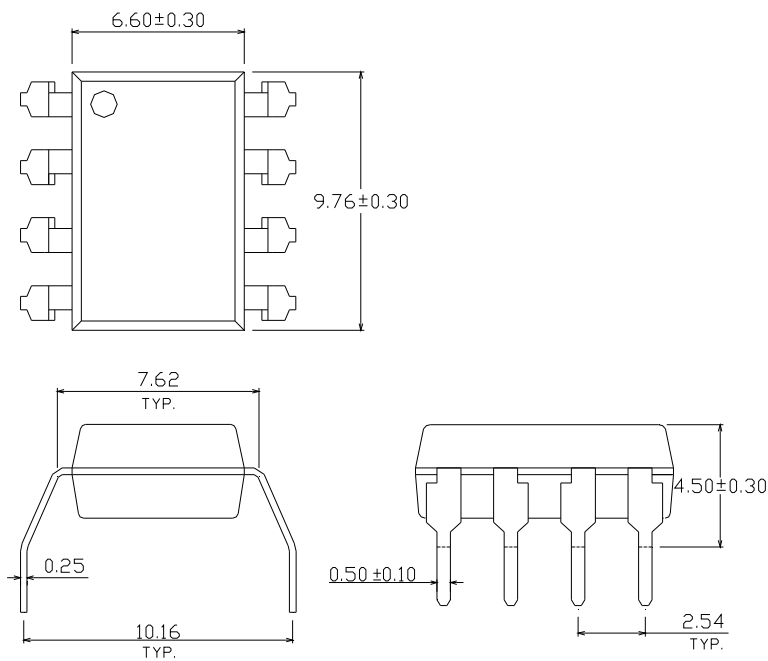
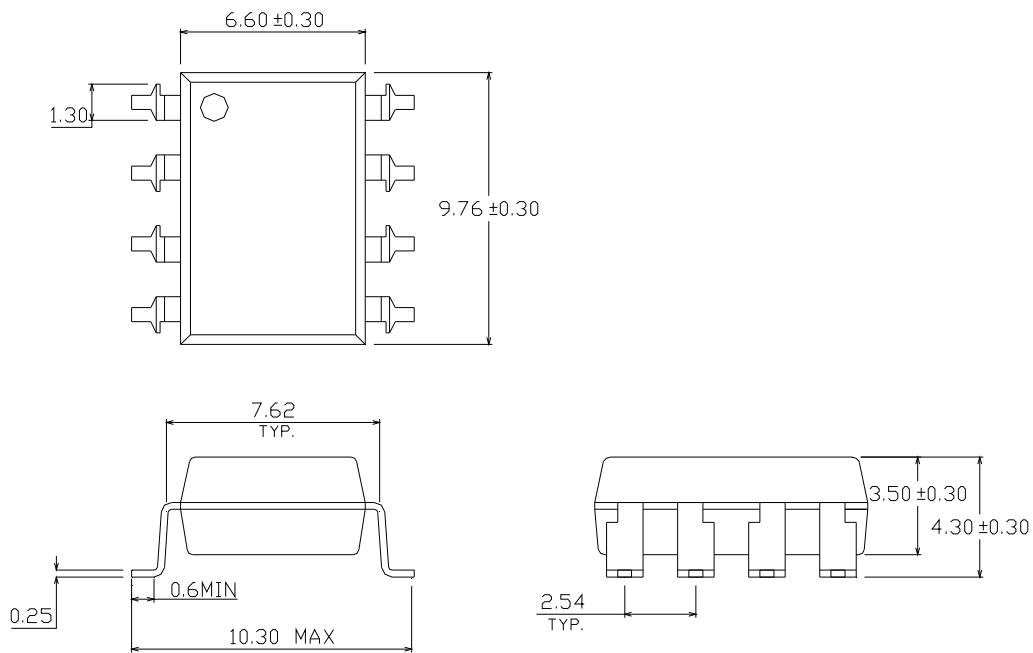| Option	Description	Packing quantity
None	Standard DIP-8	45 units per tube
M	Wide lead bend (0.4 inch spacing)	45 units per tube
S (TA)	Surface mount lead form + TA tape & reel option	1000 units per reel
S (TB)	Surface mount lead form + TB tape & reel option	1000 units per reel
S1 (TA)	Surface mount lead form (low profile) + TA tape & reel option	1000 units per reel
S1 (TB)	Surface mount lead form (low profile) + TB tape & reel option	1000 units per reel

Package Dimension
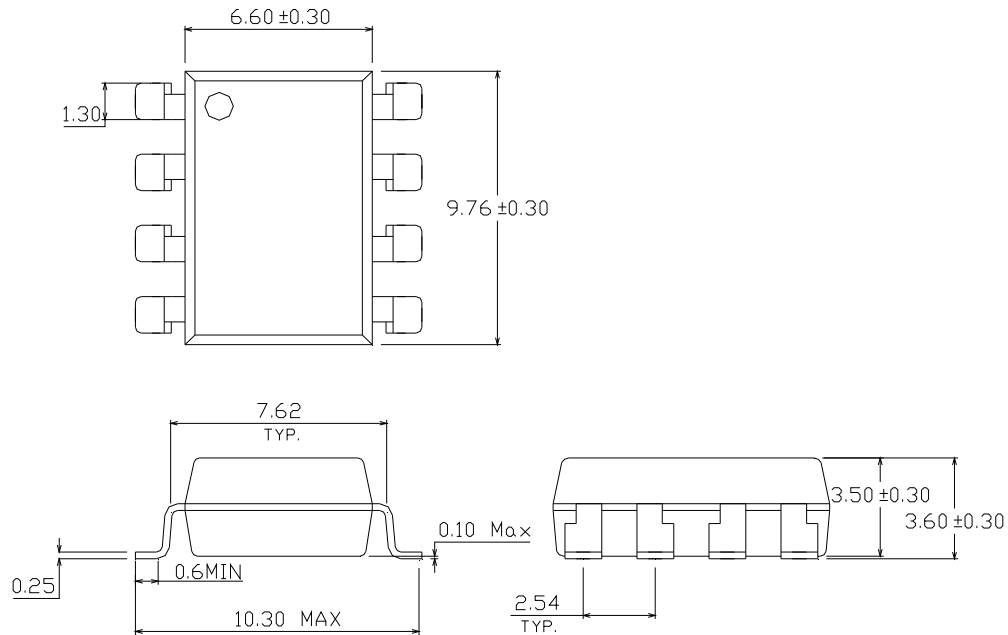**(Dimensions in mm)**

Standard DIP Type

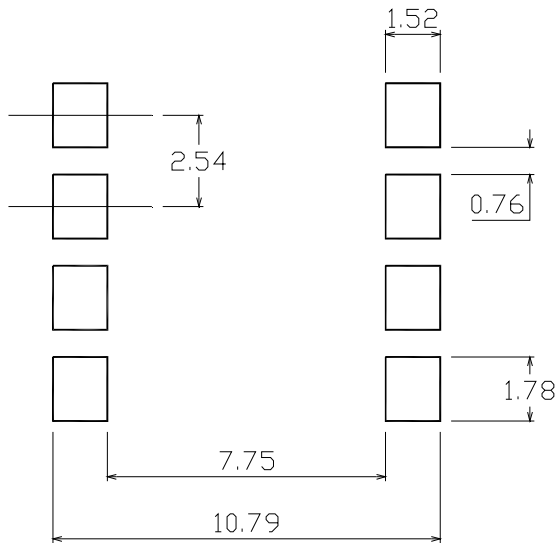6.60 ±0.30

9.76 ±0.30

7.62
TYP.

0.25   5°~15°

4.50±0.30

0.50 ±0.10

2.54
TYP.

Option M Type

6.60±0.30

9.76±0.30

7.62
TYP.

0.25

10.16
TYP.

4.50±0.30

0.50 ±0.10

2.54
TYP.

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Option S Type

Option S1 Type

Recommended pad layout for surface mount leadform

1.52

2.54

0.76

1.78

7.75

10.79

Device Marking

EL
6N138
YWWV
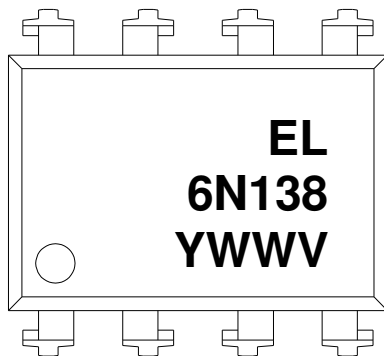
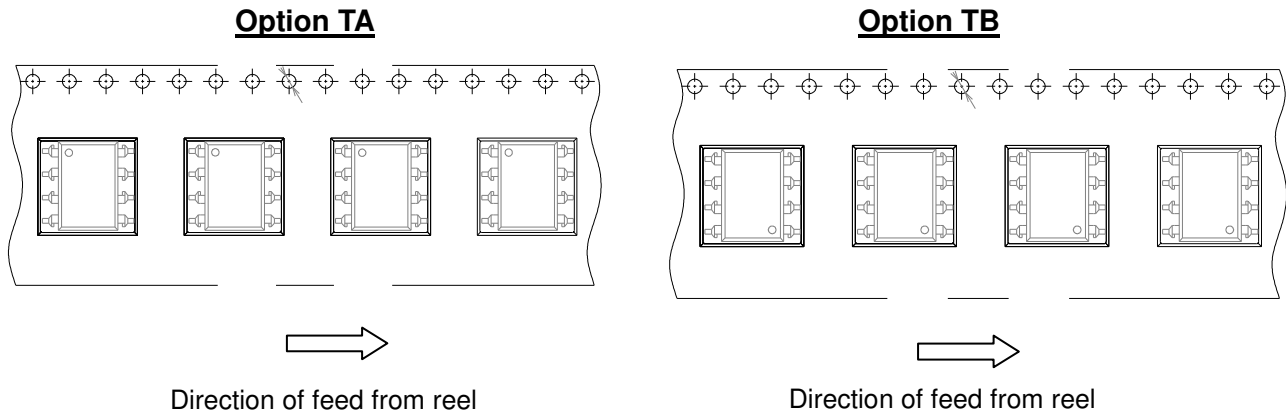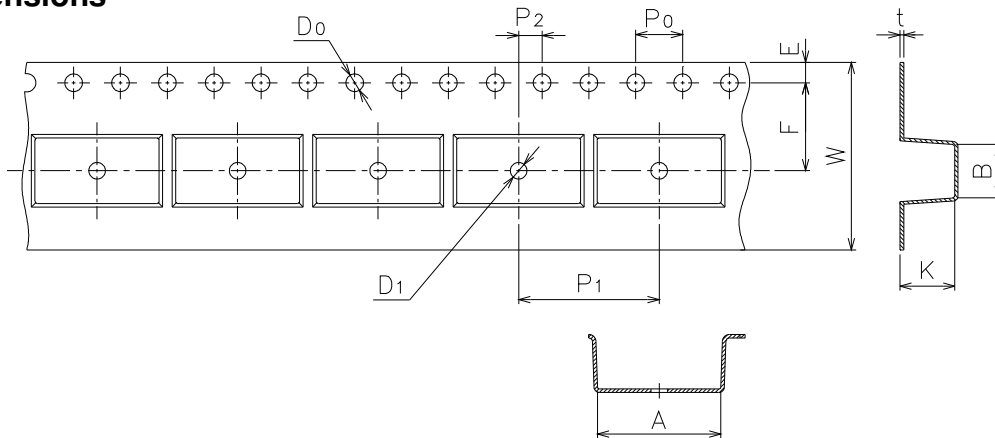**Notes**

EL   denotes EVERLIGHT
6N138   denotes Device Number
Y   denotes 1 digit Year code
WW   denotes 2 digit Week code
V   denotes VDE (Optional)

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Tape & Reel Packing Specifications

Option TA

Option TB

Direction of feed from reel

Direction of feed from reel

Tape dimensions

Dimension No.	**A**	**B**	**Do**	**D1**	**E**	**F**
Dimension(mm)	10.4±0.1	10.0±0.1	1.5+0.1/-0	1.5±0.25/-0	1.75±0.1	7.5±0.1
Dimension No.	**Po**	**P1**	**P2**	**t**	**W**	**K**
Dimension(mm)	4.0±0.1	12.0±0.1	2.0±0.05	0.4±0.05	16.0±0.3/	4.5±0.1

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Precautions for Use

1. Soldering Condition

    1.1 (A) Maximum Body Case Temperature Profile for evaluation of Reflow Profile
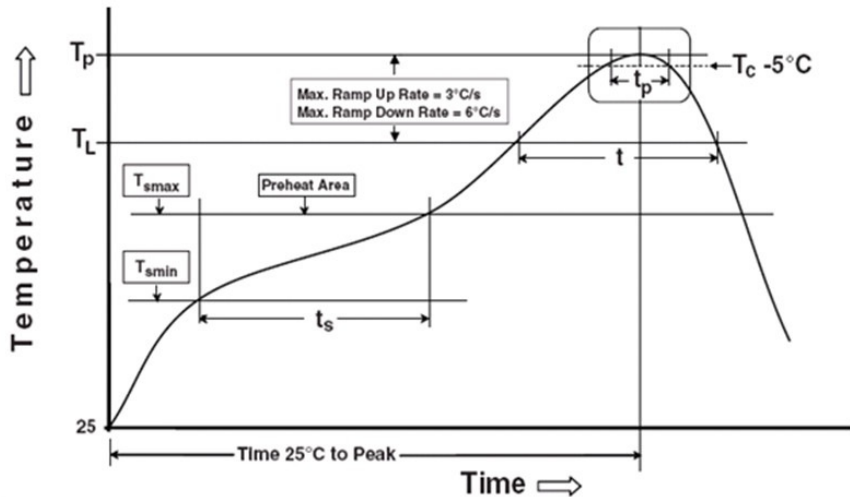
Note:

Reference: IPC/JEDEC J-STD-020D

Preheat

Temperature min (T_{smin})	150 ℃
Temperature max (T_{smax})	200℃
Time (T_{smin} to T_{smax}) (t_s)	60-120 seconds
Average ramp-up rate (T_{smax} to T_p)	3 ℃/second max

Other

Liquidus Temperature (T_L)	217 ℃
Time above Liquidus Temperature (t_L)	60-100 sec
Peak Temperature (T_P)	260℃
Time within 5 ℃ of Actual Peak Temperature: T_P - 5℃	30 s
Ramp- Down Rate from Peak Temperature	6℃ /second max.
Time 25℃ to peak temperature	8 minutes max.
Reflow times	3 times

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